

#### 12V N-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C		
10)/	8mΩ @ V <sub>GS</sub> = 4.5V	12.2A		
12V	12.5mΩ @ V <sub>GS</sub> = 2.5V	10.4A		

### **Description and Applications**

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- **Battery Management Application**
- **Power Management Functions**
- DC-DC Converters

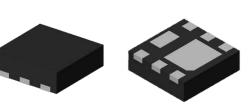
# **Features**

- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm<sup>2</sup>
- Low Gate Threshold Voltage
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMN1008UFDFQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

#### **Mechanical Data**

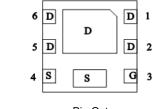
- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @4
- Weight: 0.0065 grams (Approximate)



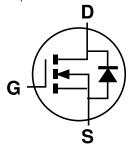
**Bottom View** 

U-DFN2020-6 (Type F)

Top View



Pin Out **Bottom View** 



Internal Schematic

### Ordering Information (Note 4)

Part Number	Reel Size (inches)	Case	Quantity per Reel
DMN1008UFDFQ-7	7	U-DFN2020-6 (Type F)	3,000
DMN1008UFDFQ-13	13	U-DFN2020-6 (Type F)	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

## **Marking Information**



8N = Product Type Marking Code YWX = Date Code Marking

Y = Year (ex: 0 = 2020)

W = Week (ex: a = Week 27; z Represents Week 52 and 53)

X = Internal Code (ex: U = Monday)

Date Gode Key												
Year	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030
Code	9	0	1	2	3	4	5	6	7	8	9	0
147												
Week	1-26				27-52			53				
Code	A-Z				a-z			Z				
Internal Code	Sı	ın	Mor	1	Tue	,	Wed	Thu		Fri		Sat
Code	П	Γ	U		V		W	X		Υ		Z

July 2020

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## **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	V <sub>DSS</sub>	12	V		
Gate-Source Voltage			$V_{GSS}$	±8	V
Continuous Drain Current, V <sub>GS</sub> = 4.5V (Note 6)	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	l <sub>D</sub>	12.2 9.8	A	
Pulsed Drain Current (380µs Pulse, Duty Cycle = 1%	I <sub>DM</sub>	60	Α		
Continuous Source-Drain Diode Current (Note 6)	Is	1.8	Α		
Avalanche Current, L = 0.1mH (Note 7)	las	16.4	Α		
Avalanche Energy, L = 0.1mH (Note 7)	Eas	13.5	mJ		

## **Thermal Characteristics**

Characteristic	Symbol	Value	Unit		
Total Power Dissipation (Note 5)	T <sub>A</sub> = +25°C	D-	0.7	W	
Total Fower Dissipation (Note 3)	T <sub>A</sub> = +70°C	PD	0.4	VV	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	Reja	168	°C/W	
Total Bower Dissination (Note 6)	T <sub>A</sub> = +25°C	D-	1.7	W	
Total Power Dissipation (Note 6)	T <sub>A</sub> = +70°C	$P_{D}$	1.0		
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	Reja	74	°C/W	
Thermal Resistance, Junction to Case (Note 6)	·	Rejc	12	°C/W	
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C	

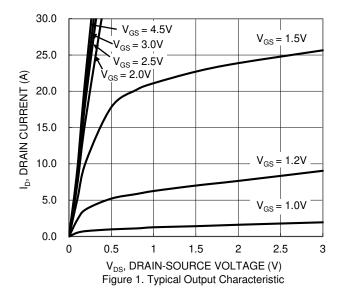
## Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	12		_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	IDSS	_	_	1	μΑ	$V_{DS} = 9.6V, V_{GS} = 0V$	
Gate-Source Leakage	lgss	_		±100	nA	$V_{GS} = \pm 8V$ , $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	0.3		1.0	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
			6.6	8		$V_{GS} = 4.5V, I_D = 5A$	
Static Drain-Source On-Resistance	RDS(ON)	_	7.6	11	mΩ	$V_{GS} = 3.0V, I_{D} = 5A$	
			8.5	12.5		$V_{GS} = 2.5V, I_{D} = 5A$	
Diode Forward Voltage	V <sub>SD</sub>	_	0.7	1.2	V	$V_{GS} = 0V$ , $I_{S} = 5A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	Ciss	_	995	_		.,	
Output Capacitance	Coss	_	305	_	pF	V <sub>DS</sub> = 6V, V <sub>GS</sub> = 0V, f = 1.0MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>	_	270	_			
Gate Resistance	Rg	_	1.5	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	_	13.6	_			
Total Gate Charge (V <sub>GS</sub> = 8V)	Qg	_	23.4	_	nC	\/ C\/  -	
Gate-Source Charge	Qgs	_	1.3	_	IIC	$V_{DS} = 6V$ , $I_D = 5A$	
Gate-Drain Charge	Qgd	_	3.3	_			
Turn-On Delay Time	td(ON)	_	3.5	_			
Turn-On Rise Time	tR	_	6.6	_		$V_{DS} = 6V, V_{GS} = 4.5V,$	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	17.5	_	ns	$R_G = 2\Omega$ , $I_D = 5A$	
Turn-Off Fall Time	tF	_	7.5	_			
Reverse Recovery Time	t <sub>RR</sub>	_	15	_	ns	I <sub>F</sub> = 5A, di/dt = 200A/μs	
Reverse Recovery Charge	Qrr	_	4	_	nC	IF = 5A, di/dt = 200A/μs	

Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
I<sub>AS</sub> and E<sub>AS</sub> ratings are based on low frequency and duty cycles to keep T<sub>J</sub> = +25°C.
Short duration pulse test used to minimize self-heating effect.
Guaranteed by design. Not subject to product testing.







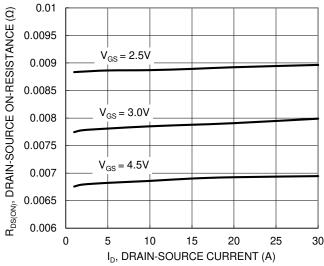


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

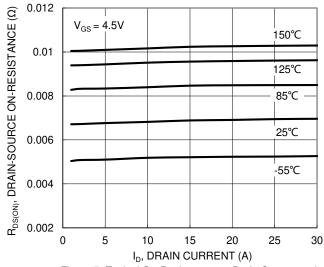
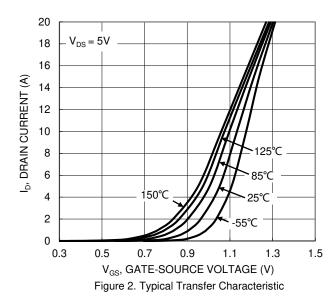


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature



0.08 0.08 0.06 0.004 0.002 0.0

Figure 4. Typical Transfer Characteristic

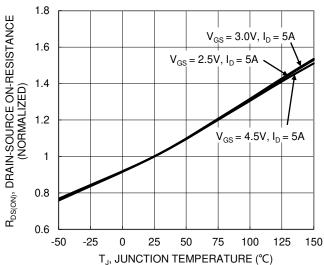
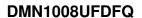


Figure 6. On-Resistance Variation with Junction Temperature





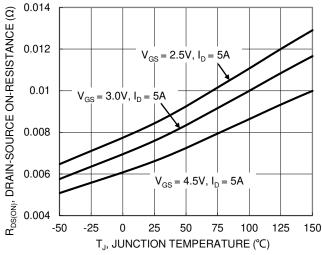


Figure 7. On-Resistance Variation with Junction Temperature

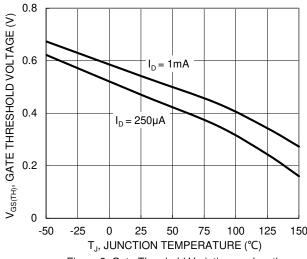


Figure 8. Gate Threshold Variation vs. Junction Temperature

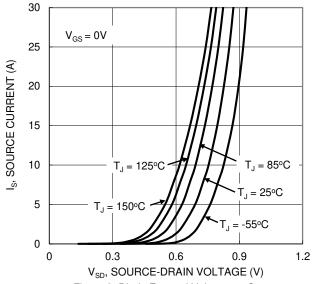
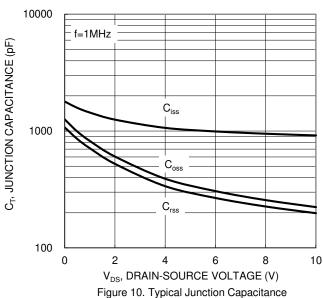


Figure 9. Diode Forward Voltage vs. Current



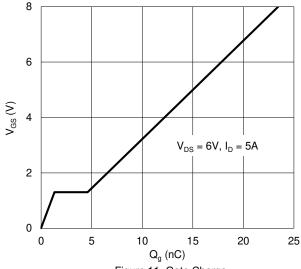
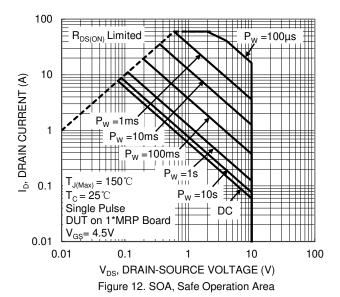


Figure 11. Gate Charge





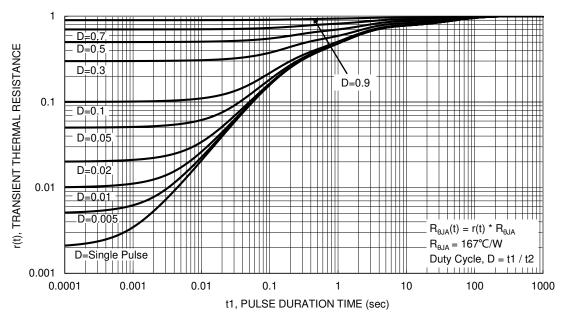


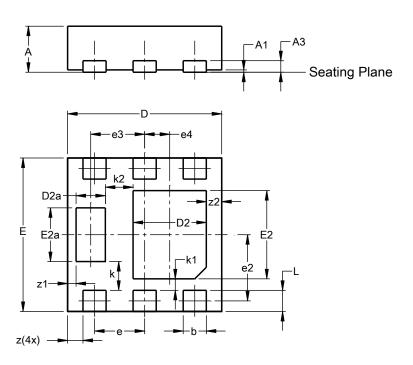
Figure 13. Transient Thermal Resistance



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### U-DFN2020-6 (Type F)

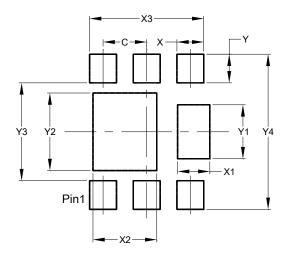


U-DFN2020-6							
(Type F)							
Dim	Min	Max	Тур				
Α	0.57	0.63	0.60				
A1	0.00	0.05	0.03				
A3	-	-	0.15				
b	0.25	0.35	0.30				
D	1.95	2.05	2.00				
D2	0.85	1.05	0.95				
D2a	0.33	0.43	0.38				
E	1.95	2.05	2.00				
E2	1.05	1.25	1.15				
E2a	0.65	0.75	0.70				
е		0.65 BS	С				
e2	(	).863 BS	SC				
е3		0.70 BS	С				
e4	(	).325 BS	Ö				
k		0.37 BS	C				
k1	0.15 BSC						
k2	0.36 BSC						
L	0.225 0.325 0.275						
Z	0.20 BSC						
z1	0.110 BSC						
z2	0.20 BSC						
All Dimensions in mm							

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### U-DFN2020-6 (Type F)



Dimensions	Value
Dilliciisions	(in mm)
С	0.650
X	0.400
X1	0.480
X2	0.950
Х3	1.700
Υ	0.425
Y1	0.800
Y2	1.150
Y3	1.450
Y4	2.300



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